



**OPERATING INSTRUCTIONS  
PACE PART NUMBER 6016-0003-P1  
MANUAL NUMBER 5050-0055 Rev.C**

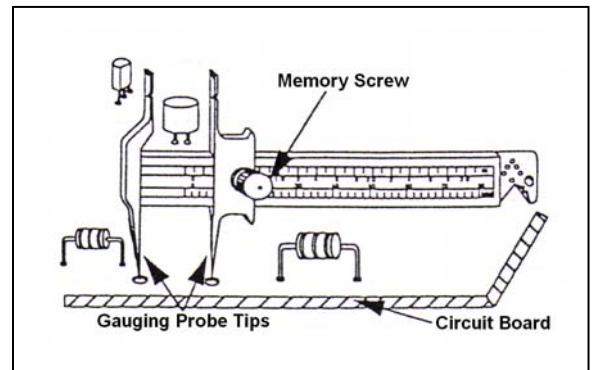
The PACE ComForm I tool may be used to form component leads to facilitate PCB insertion and to perform general measurements. Read this manual thoroughly before use.

**MEASUREMENT**

The Calibrated Scale on the ComForm I allows the user to measure the approximate sizes of components and approximate distances point to point in 1/10 inch and/or 1 millimeter increments.

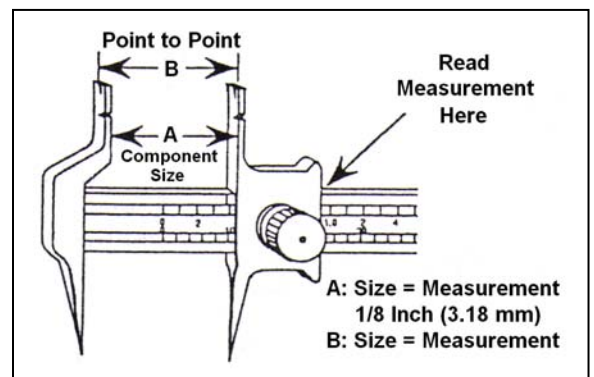
**MEASURING HOLE-TO-HOLE SPACING**

1. Place Gauging Probe tips into PCB holes where component is to be mounted.
2. Tighten Memory Screw.



**MEASURING COMPONENT SIZE**

1. Place component (or other object) between the 2 Forming Heads.
2. Read measurement on Calibrated Scale at right edge of movable Forming Head.
3. Deduct 1/8 inch (3.18 mm) from measurement to obtain approximate size.

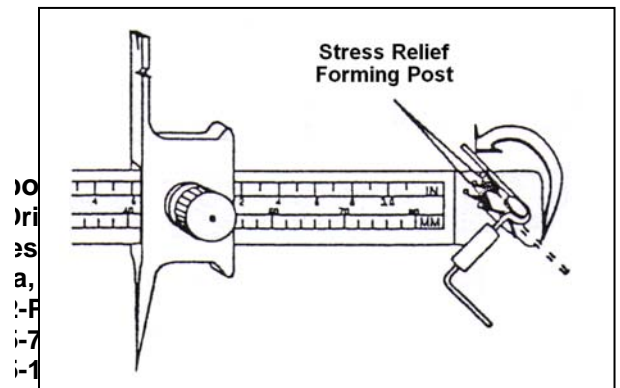


**MEASURING POINT TO POINT**

1. Place the 2 Forming Heads between the points to be measured.
2. Read measurement on Calibrated Scale at right edge of movable Forming Head.

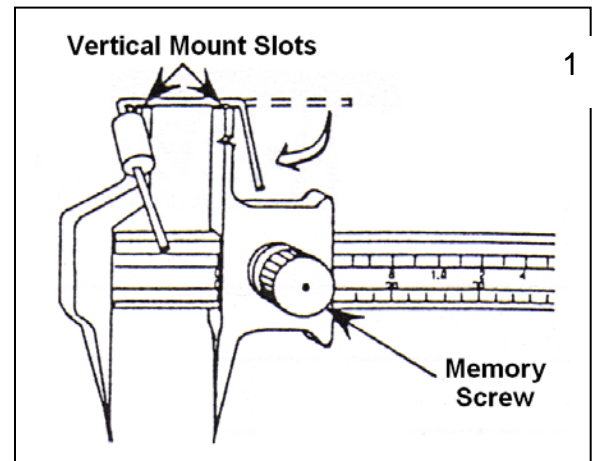
**FORMING STRESS RELIEF LOOPS**

1. Measure Hole-To-Hole spacing.
2. Subtract 1/10" (1 mark on inch scale) from Calibrated Scale for each loop to be formed. Adjust Forming Head spacing and tighten Memory Screw.
3. Form 90° bends as previously described.
4. Place 90° bend lead(s) in Stress Relief Forming Posts and form Stress Relief Loop(s) as shown.



## FORMING LEADS FOR VERTICAL MOUNT

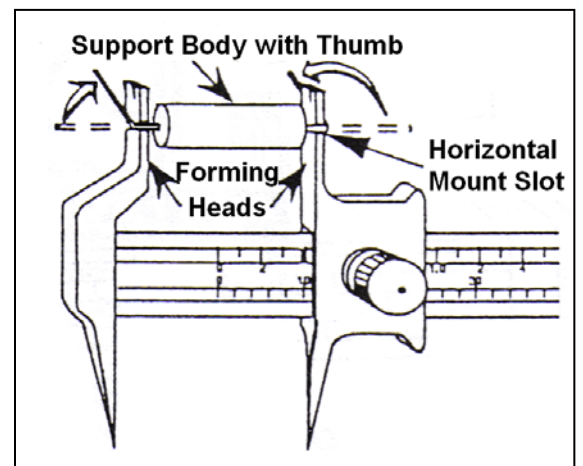
1. Place component in V shaped Vertical Mount Slots with component body flush to both Forming heads.
2. Tighten Memory Screw.
3. Make one 90° bend as shown.
4. Remove component and measure Hole-To-Hole spacing.
5. Tighten memory Screw.
6. Place component in V shaped Vertical Mount Slots and make a second 90° bend in the same lead as shown.



## FORMING 90° BENDS

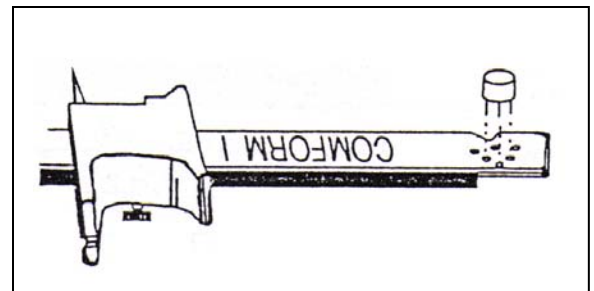
1. Measure Hole-To-Hole spacing.
2. Center component in V shaped Horizontal Mount Slots.
3. Support the component body with thumb and form leads upward toward the top of the Forming Heads. Do not form leads toward the bottom of the V shaped slot.

NOTE: Forming Heads automatically compensate for a minimum 1/16" clearance from component body to lead bend radius.



## TRANSISTOR LEAD FORMING

1. Orient the transistor leads to match hole configurations on the end of the ComForm I next to the Stress Relief Forming Posts.
2. Insert Leads through the holes which most closely match the PCB component pad configuration.
3. Leads may be cut to desired length at this point



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